

规格书编号

SPEC NO :

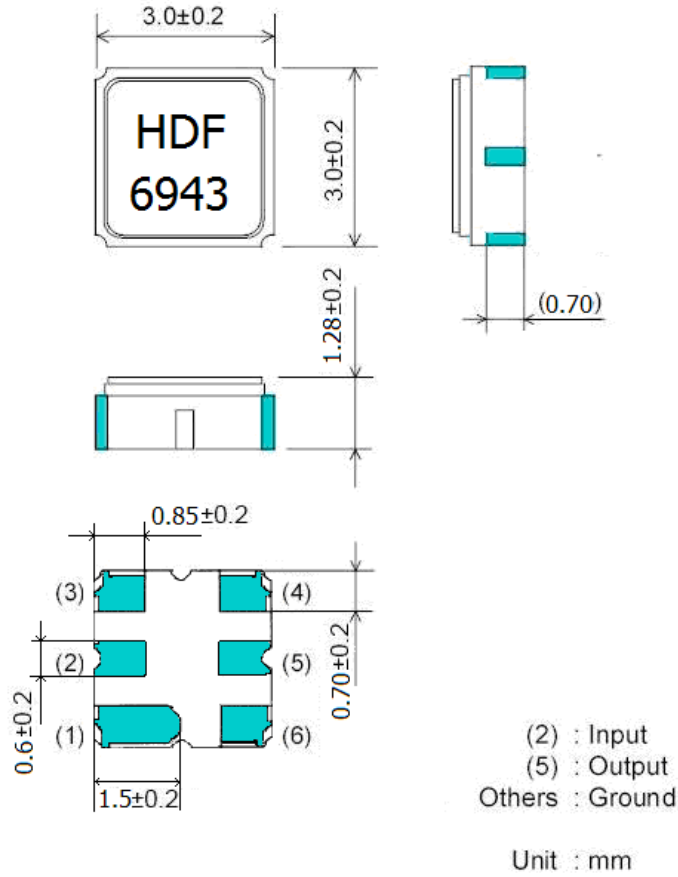
产品规格书 SPECIFICATION

CUSTOMER 客户: _____
PRODUCT 产品: _____ SAW FILTER _____
MODEL NO 型号: _____ HDF915C1 SMD-6 _____
MARKING 印字: _____ HDF6943 _____
PREPARED 编制: 何 强 CHECKED 审核: 邓 攀
APPROVED 批准: [Signature] DATE 日期: 2010-6-1

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. Package Dimension



2. Marking: HDF6943

HD: Brand
 F : Filter
 6: SMD-6
 943 : No.

3. Performance

3.1 Application

Low-loss RF filter for remote control receivers
 Center Frequency: 915 MHz

3.2 Maximum Rating

Operation Temperature Range	-40°C to +85°C
Storage Temperature Range	-40°C to +85°C
DC. Permissible Voltage	5V DC. max.
Maximum Input Power	15dBm

3.3 Electronic Characteristics

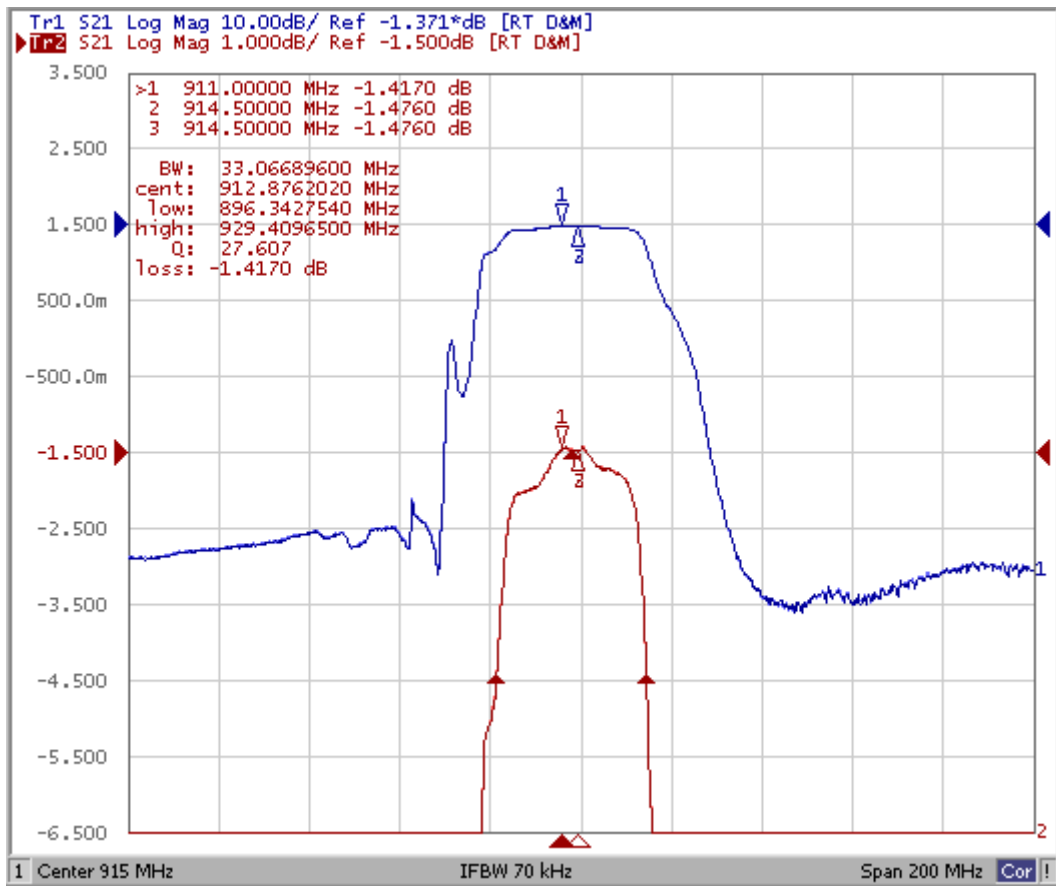
Temperature range for specification: T = -40 °C to +85 °C

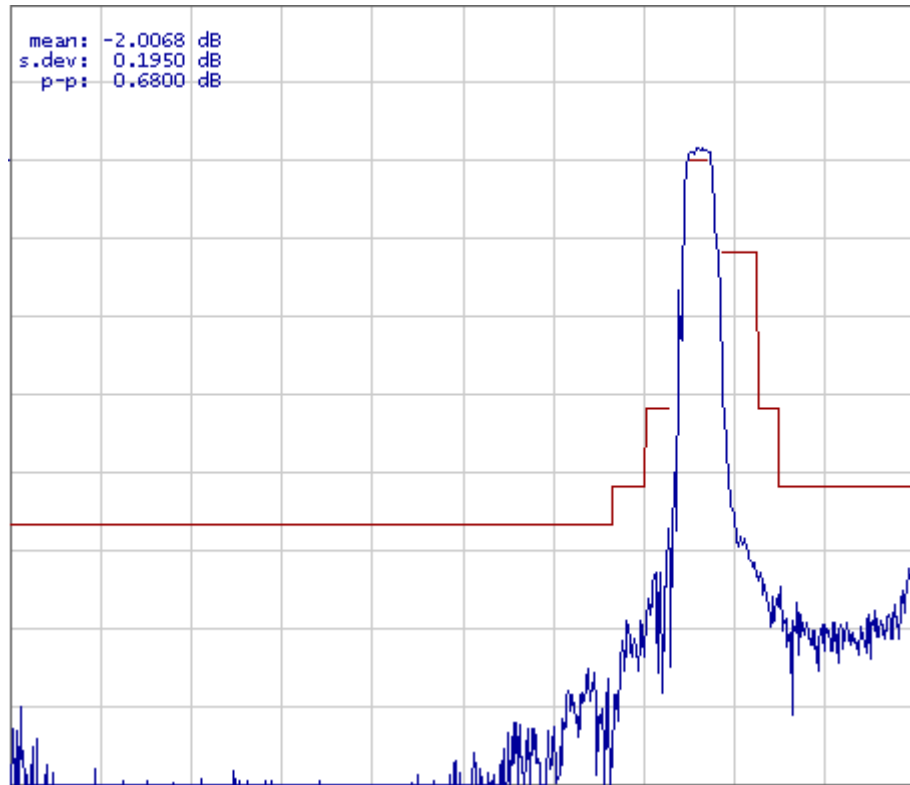
Terminating source impedance: Z_s = 50 Ω

Terminating load impedance: Z_L = 50Ω

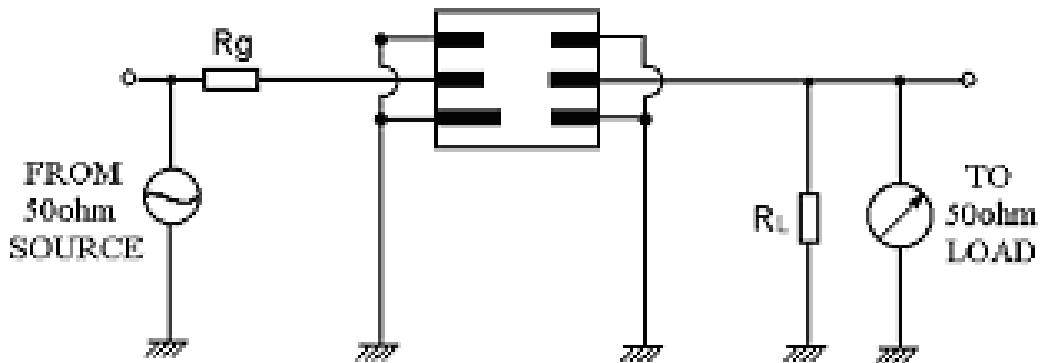
	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	-	915	-
Insertion Loss (902~928MHz)	dB		2.4	3.5
Amplitude Ripple (902~928MHz)	dB		0.9	1.8
Relative Attenuation				
10.0 ~ 800.0 MHz	dB	50	55	-
800.0~845.0MHz		45	50	
845.0 MHz ~ 880.0 MHz		33	43	
947.0 MHz ~ 992.0 MHz		25	35	
992.0 MHz ~ 1020.0 MHz		35	45	
1020.0 MHz ~ 1200.0 MHz		45	50	
Input/Output Impedance	Ohms		50	

3.4 Frequency Characteristics





3.5 Test Circuit



4. ENVIRONMENTAL CHARACTERISTICS

4-1 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of $+25^{\circ}\text{C}$ for 5 Minutes and a higher temperature of $+85^{\circ}\text{C}$ for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 3.3.

4-2 Resistance to solder heat

Submerge the device terminals into the solder bath at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications

in 3.3.

4-3 Solderability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 3.3.

4-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 3.3.

4-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 3.3.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

6. Packing

6.1 Dimensions

(1) Carrier Tape: Figure 1

(2) Reel: Figure 2

(3) The product shall be packed properly not to be damaged during transportation and storage.

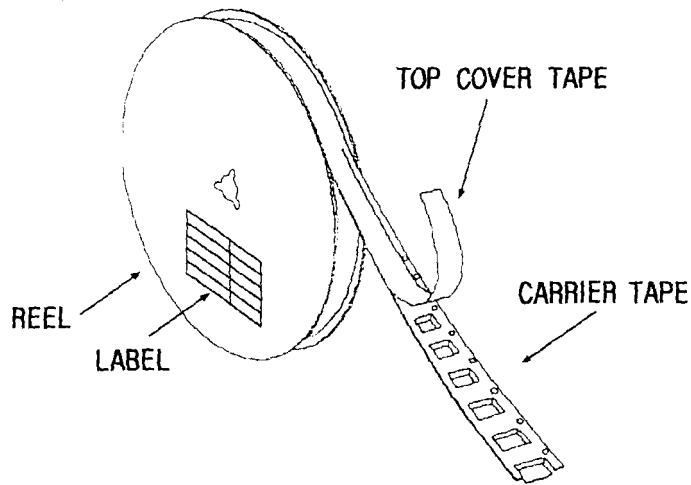
6.2 Reeling Quantity

1000 pcs/reel 7"

3000 pcs/reel 13"

6.3 Taping Structure

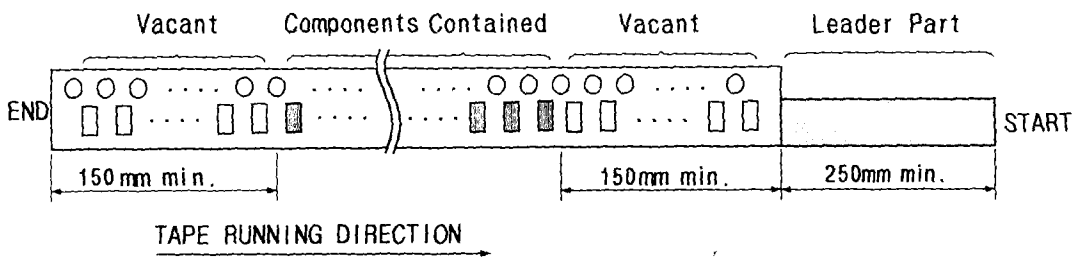
(1) The tape shall be wound around the reel in the direction shown below.



(2) Label

Device Name	
User Product Name	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.

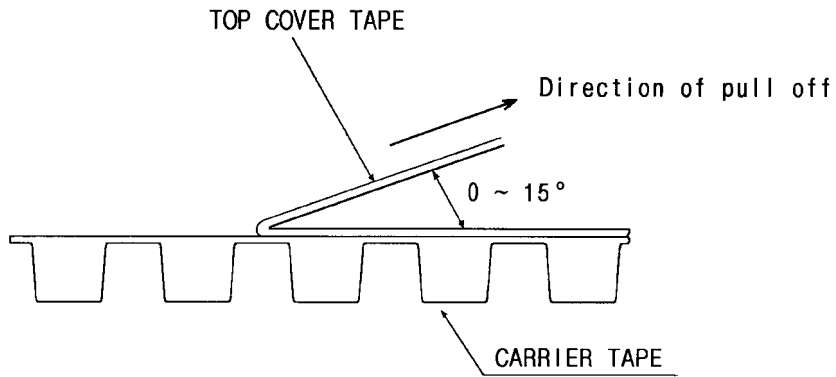


7. TAPE SPECIFICATIONS

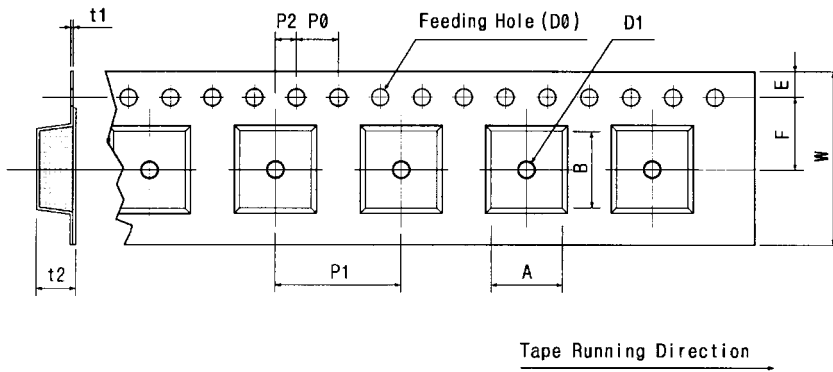
7.1 Tensile Strength of Carrier Tape: 4.4N/mm width

7.2 Top Cover Tape Adhesion (See the below figure)

- (1) pull off angle: 0~15°
- (2) speed: 300mm/min.
- (3) force: 20~70g



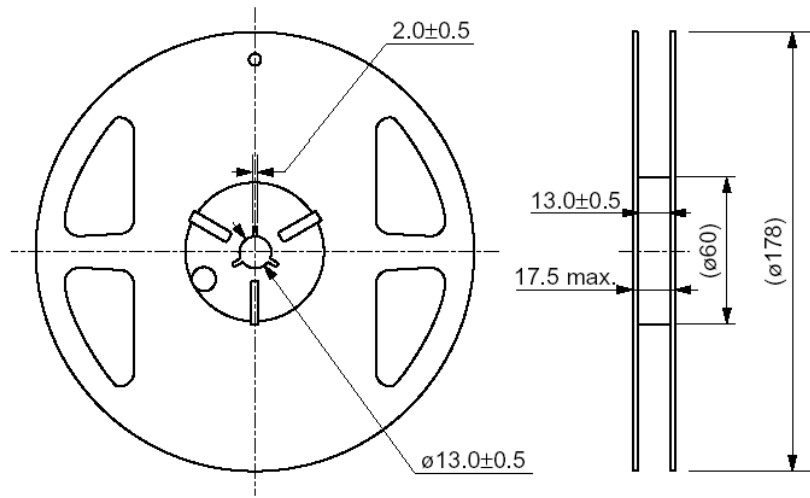
[Figure 1] Carrier Tape Dimensions



[Unit:mm]

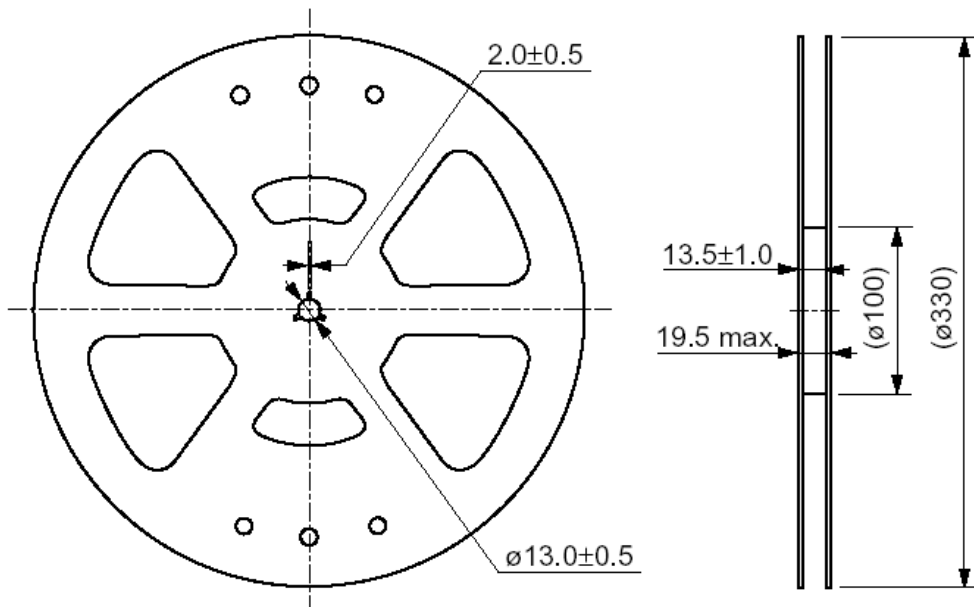
W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.0	5.5	1.75	4.0	4.0	2.0	Ø1.5	Ø1.0	0.3	1.25	3.3±	3.3
±	±	±	±	±	±0.05	±0.1	±	±	±	0.1	±
0.3	0.05	0.1	0.1	0.1			0.25	0.05	0.1		0.1

[Figure 2]



∅178 Reel Dimension

(in mm)



∅330 Reel Dimension

(in mm)